

## Product Compliance Declaration

Please see [www.molex.com](http://www.molex.com) for the most up-to-date information.

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### Contact Information

**Name** Molex Product Compliance **E-Mail** Product.Compliance@molex.com

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### Part Information

**Part Number** 0015978107 **Part Weight** 4.577763G

**Part Name** MiniFit TPA RA Hdr /Flg Gold 10Ckt

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### Product Composition

Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
MiniFit TPA RA Hdr /Flg Gold 10Ckt	Assembly		100	4.577763
".650 X .042 SQ BANDO 228PLT 30""SAu"	Assembly		17.2573	0.79
0.650 X .042 Sq Bando Pin 999	Component		17.1481	0.785
Cartridge Brass 70% Unplated	Material		17.1481	0.785
Copper	Substance	7440-50-8	12.0037	0.5495
Zinc (metal)	Substance	7440-66-6	5.1444	0.2355
Gold Plating	Material		0.0243	0.001113
Gold	Substance	7440-57-5	0.0242	0.001107
Nickel	Substance	7440-02-0	6E-5	0.000003
Cobalt	Substance	7440-48-4	6E-5	0.000003
Tin Plating	Material		0.0247	0.00113
Tin	Substance	7440-31-5	0.0247	0.00113
Nickel Plating	Material		0.0602	0.002758

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Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
Nickel	Substance	7440-02-0	0.0602	0.002757
Further Additives	Substance	system	6E-6	3E-7
"1.083 X .042 SQ BANDO 228PLT 30 Au"	Assembly		29.1575	1.334762
1.083 X .042 Sq Bando Pin 999	Component		28.9443	1.325
Cartridge Brass 70% Unplated	Material		28.9443	1.325
Copper	Substance	7440-50-8	20.261	0.9275
Zinc (metal)	Substance	7440-66-6	8.6833	0.3975
Tin Plating	Material		0.036	0.001649
Tin	Substance	7440-31-5	0.036	0.001649
Nickel Plating	Material		0.142	0.0065
Nickel	Substance	7440-02-0	0.142	0.006499
Further Additives	Substance	system	1E-5	7E-7
Gold Plating	Material		0.0352	0.001613
Gold	Substance	7440-57-5	0.0351	0.001605
Nickel	Substance	7440-02-0	9E-5	0.000004
Cobalt	Substance	7440-48-4	9E-5	0.000004
MiniFit TPA RA Hdr /Flg 10Ckt	Component		53.5851	2.453
PBT UF BLACK	Material		53.5851	2.453
PBT	Substance		35.0983	1.606715
Antimonytrioxide	Substance	1309-64-4	5.3585	0.2453
Further Additives	Substance	system	5.0906	0.233035
Flame Retardant, ISO 1043-4 FR(17)	Substance		8.0378	0.36795

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**ROHS Declaration Information**

**Regulatory Revision**    2011/65/EU

**Compliance Status**    Compliant

**Contained Substances Exceeding Threshold**

None

**Exemptions**

None

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**REACH-SVHC Declaration Information**

**Regulatory Revision**    ED/30/2017 (7 July 2017)

**Contained Substances Exceeding Threshold**

None

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**GADSL Declaration Information**

**Regulatory Revision**    GADSL imported from IMDS

**Contained Substances Exceeding Threshold**

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Lead	Cartridge Brass 70% (CA260)	*Note	350	Yes
Lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	150	Yes
Antimonytrioxide	PBT UF BLACK	*Note	100,000	Yes
Nickel	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
Nickel	Ep-Ni	*Note	997,500	Yes
Cobalt	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
Copper	Cartridge Brass 70% (CA260)	*Note	700,000	Yes

**\*Note:** For GADSL substance declarable/prohibited threshold values, please reference <http://www.gadsl.org/>

Exemptions

Part Name	Exemption
Cartridge Brass 70% (CA260)	44 Concentration within acceptable GADSL limits
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits
e-plate Au (Hardgold) (electrodeposited Hardgold Coatings)	34 Not applicable
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)


HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Bromine and its compounds	PBT UF BLACK	900	150,000	Yes
Bromine and Chlorine combined	PBT UF BLACK	1,500	150,000	Yes

China ROHS Declaration Information

Part Number     0015978107		<b>Hazardous Substances</b>					
Part Name        MiniFit TPA RA Hdr /Flg Gold 10Ckt							
Part Information							
Components		Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
MiniFit TPA RA Hdr /Flg Gold 10Ckt		O	O	O	O	O	O
".650 X .042 SQ BANDO 228PLT 30""SAu"		O	O	O	O	O	O
0.650 X .042 Sq Bando Pin 999		O	O	O	O	O	O
"1.083 X .042 SQ BANDO 228PLT 30 Au"		O	O	O	O	O	O
1.083 X .042 Sq Bando Pin 999		O	O	O	O	O	O
MiniFit TPA RA Hdr /Flg 10Ckt		O	O	O	O	O	O

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## Process Information

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A
Solder Alloy	N/A
Process Capability	WAVE
Maximum Exposure Time (seconds)	005
Maximum Process Temperature (C)	260
Maximum Cycles at Reflow Temperature	001
J-STD-020 Moisture Sensitivity Level	N/A

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